



Isolation Voltage	V_{iso}	5000 ^V	Vrms
Operating Temperature	T_{opr}	-40 ~ 110	°C
Junction Temperature	T_j	125	°C
Storage Temperature	T_{stg}	-40 ~ 125	°C
Soldering Temperature	T_{sol}	260	°C
Peak pulse voltage ($\leq 25\mu s$; non-repetitive, off-state)	V_{pp}	3	kV

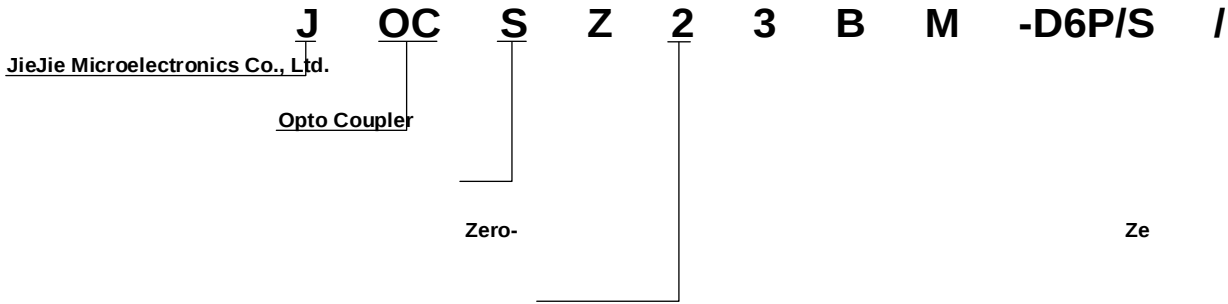
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Parameter Symbol Condition Min. Typ. . . . !



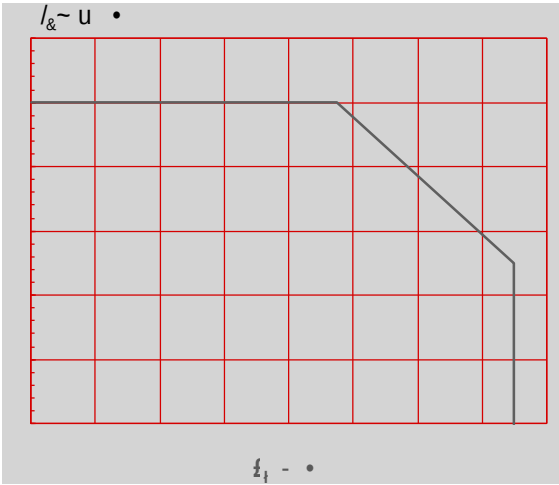
h w59wLbD LbC h wa ! £ L h b





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FIG.1: Max. Allowable LED Forward Current vs. Ambient Temperature



td.

ambient

FIG.7: On-state characteristics

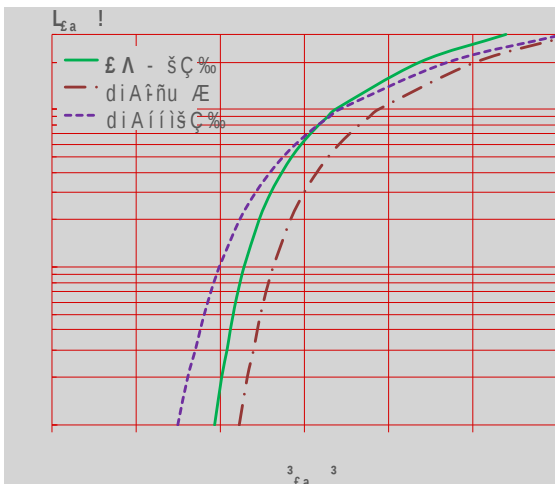


FIG.8: Normalized Holding Current vs. Ambient Temperature

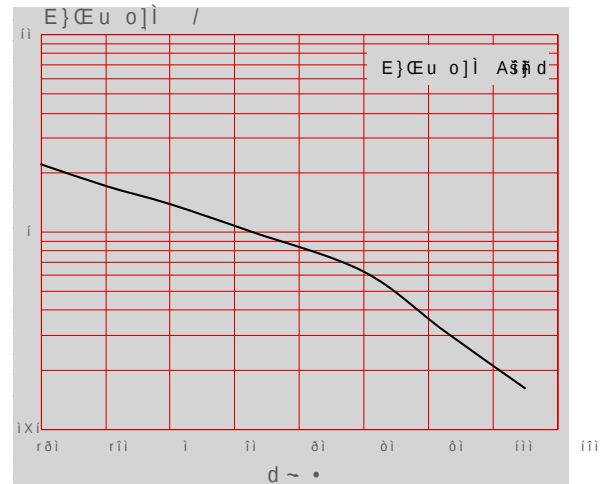


FIG.9: Turn On Time vs. Forward Current

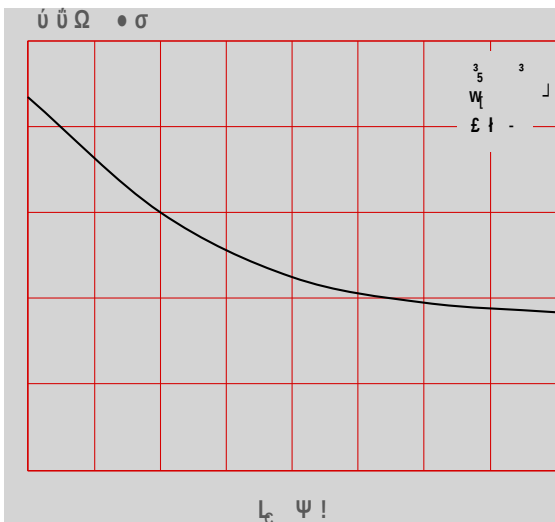
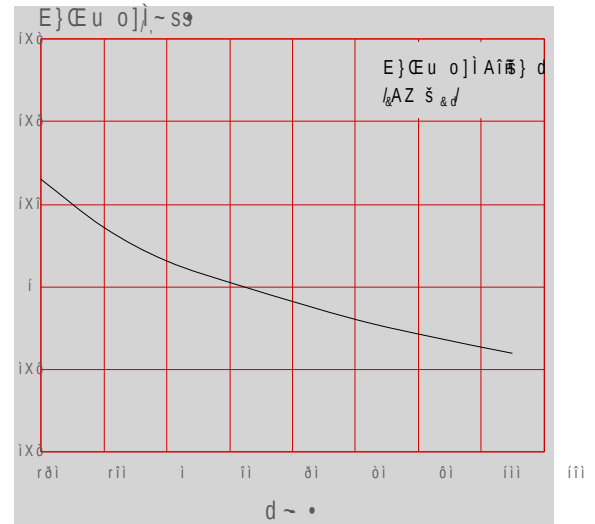


FIG.10: Normalized Inhibit Voltage vs. Ambient Temperature



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FIG.11: Test Circuits o f Turn On Time

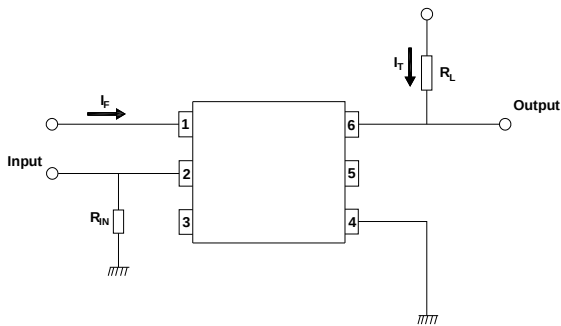


FIG.12: Wave f orms o f Turn On Time

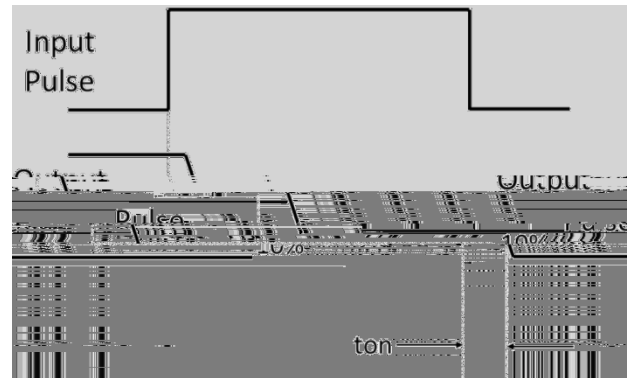
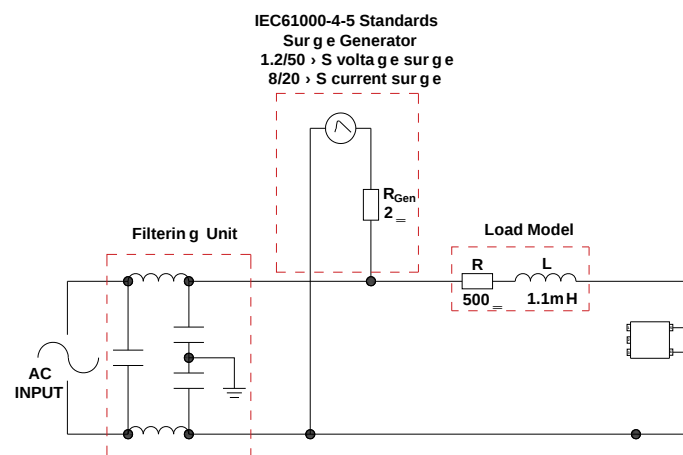


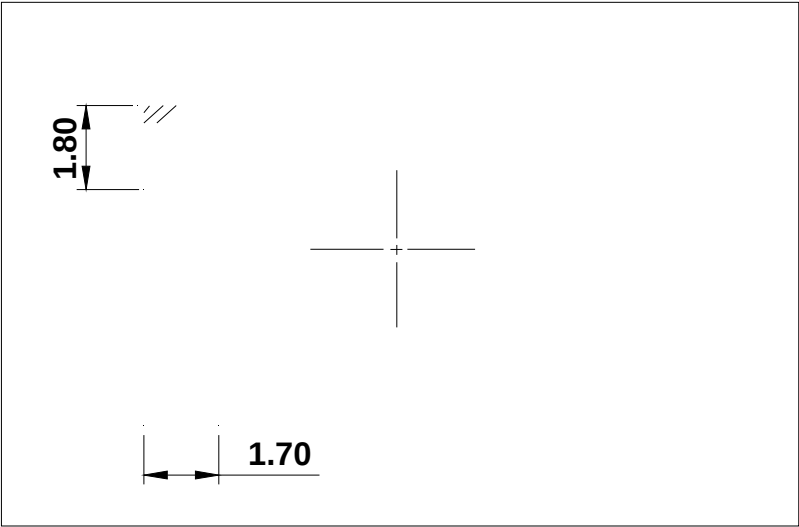
FIG.13: Test circuit f or inductive and resistive loads to IEC-61000-4-5 standards





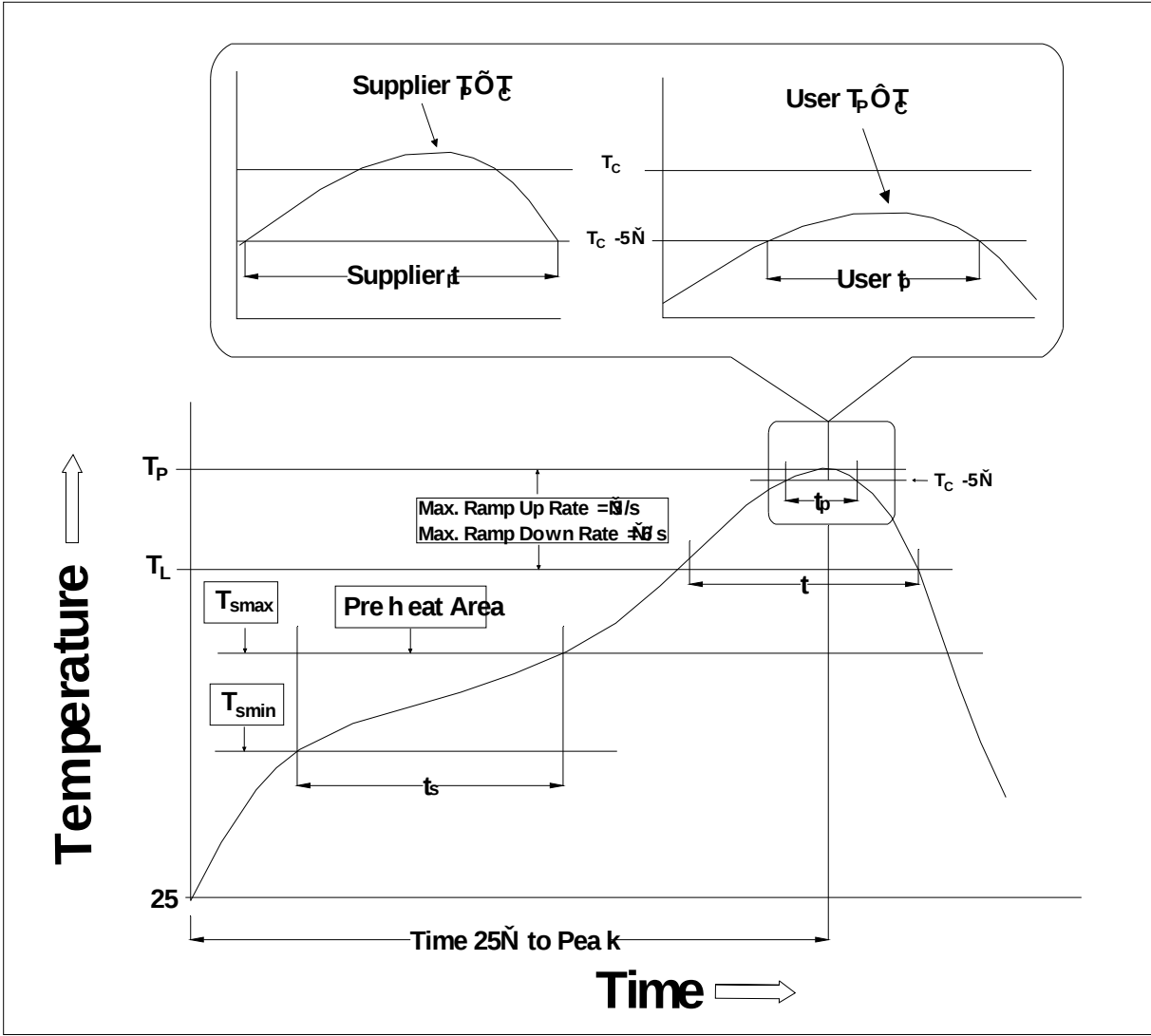
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Option SMD



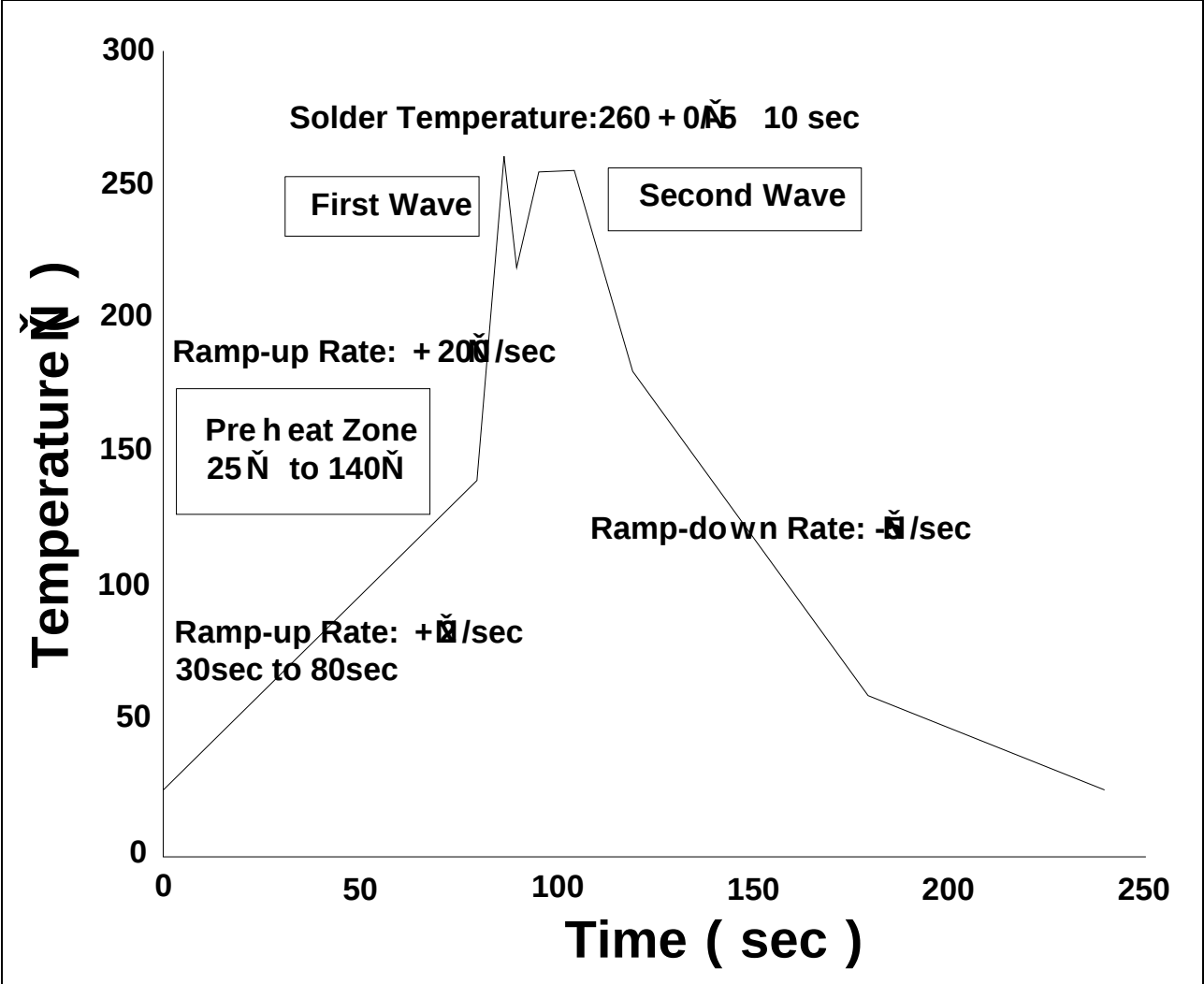
JOC SZ23BM

w9C [h ´ LbCh wa ! £ L h b



Temperature Min. (T_{smin})	150 $^\circ\text{N}$
Temperature Max. (T_{smax})	200 $^\circ\text{N}$
Time (t_s) f rom (T_{smin} to T_{smax})	60-120 seconds
Ramp-up Rate (t_L to t_P)	3 $^\circ\text{N}$ /second max.
Li q uidus Temperature (T_L)	217 $^\circ\text{N}$
Time (t_L) Maintained Above (T_L)	60-120 seconds
Pea k Body Pac k a g e Temperature	260 $^\circ\text{N}$ + 0 $^\circ\text{N}$ / -5 $^\circ\text{N}$
Time (t_P) wit h T_P 260 $^\circ\text{N}$	10 seconds
Ramp-down Rate (T_P to T_L)	6 $^\circ\text{N}$ /second max.

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Soldering Temperature	360 ± 5°C
Soldering Time	3s max.



Note:

1. Reflow soldering is recommended at the temperatures and time, no more than three times.
2. Avoid direct contact between the epoxy body